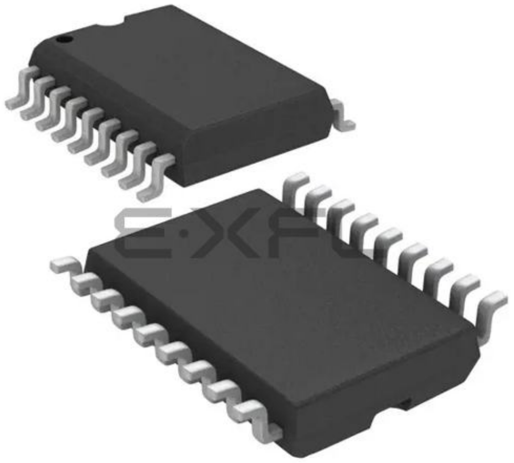
Microchip Technology - DSPIC33FJ32GP101T-I/SO Datasheet



What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

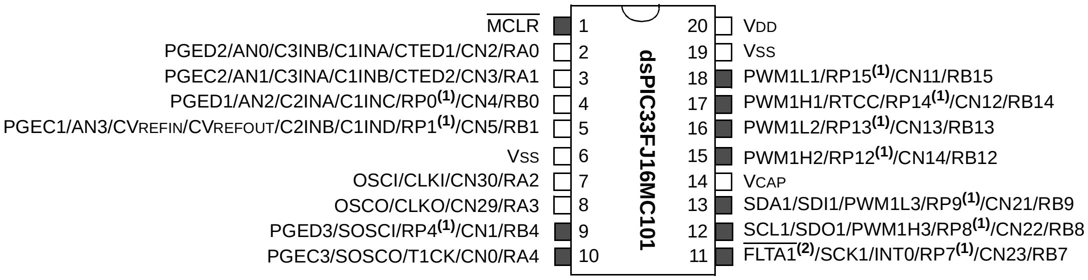
Applications of "Embedded - Microcontrollers"

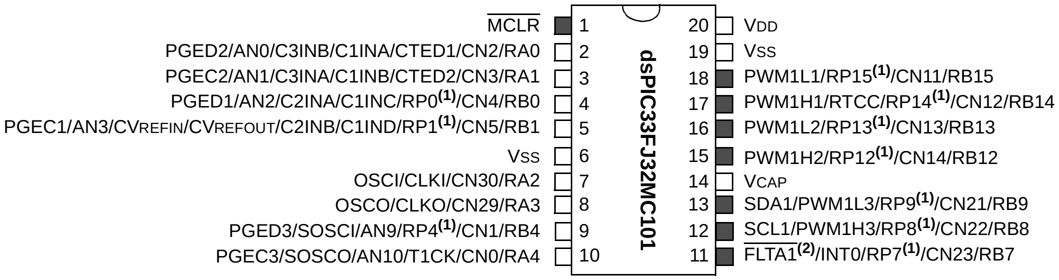
Details	
Product Status	Obsolete
Core Processor	dsPIC
Core Size	16-Bit
Speed	16 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	13
Program Memory Size	32KB (11K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 6x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	18-SOIC (0.295", 7.50mm Width)
Supplier Device Package	18-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj32gp101t-i-so

Pin Diagrams (Continued)

20-Pin PDIP/SOIC/SSOP

■ = Pins are up to 5V tolerant


dsPIC33FJ16MC101
MCLR 1
PGED2/AN0/C3INB/C1INA/CTED1/CN2/RA0 2
PGEC2/AN1/C3INA/C1INB/CTED2/CN3/RA1 3
PGED1/AN2/C2INA/C1INC/RP0(1)/CN4/RB0 4
PGEC1/AN3/CVREFIN/CVREFOUT/C2INB/C1IND/RP1(1)/CN5/RB1 5
VSS 6
OSCI/CLKI/CN30/RA2 7
OSCO/CLKO/CN29/RA3 8
PGED3/SOSCI/RP4(1)/CN1/RB4 9
PGEC3/SOSCO/T1CK/CN0/RA4 10
20 VDD
19 VSS
18 PWM1L1/RP15(1)/CN11/RB15
17 PWM1H1/RTCC/RP14(1)/CN12/RB14
16 PWM1L2/RP13(1)/CN13/RB13
15 PWM1H2/RP12(1)/CN14/RB12
14 VCAP
13 SDA1/SDI1/PWM1L3/RP9(1)/CN21/RB9
12 SCL1/SDO1/PWM1H3/RP8(1)/CN22/RB8
11 FLTA1(2)/SCK1/INT0/RP7(1)/CN23/RB7


dsPIC33FJ32MC101
MCLR 1
PGED2/AN0/C3INB/C1INA/CTED1/CN2/RA0 2
PGEC2/AN1/C3INA/C1INB/CTED2/CN3/RA1 3
PGED1/AN2/C2INA/C1INC/RP0(1)/CN4/RB0 4
PGEC1/AN3/CVREFIN/CVREFOUT/C2INB/C1IND/RP1(1)/CN5/RB1 5
VSS 6
OSCI/CLKI/CN30/RA2 7
OSCO/CLKO/CN29/RA3 8
PGED3/SOSCI/AN9/RP4(1)/CN1/RB4 9
PGEC3/SOSCO/AN10/T1CK/CN0/RA4 10
20 VDD
19 VSS
18 PWM1L1/RP15(1)/CN11/RB15
17 PWM1H1/RTCC/RP14(1)/CN12/RB14
16 PWM1L2/RP13(1)/CN13/RB13
15 PWM1H2/RP12(1)/CN14/RB12
14 VCAP
13 SDA1/PWM1L3/RP9(1)/CN21/RB9
12 SCL1/PWM1H3/RP8(1)/CN22/RB8
11 FLTA1(2)/INT0/RP7(1)/CN23/RB7

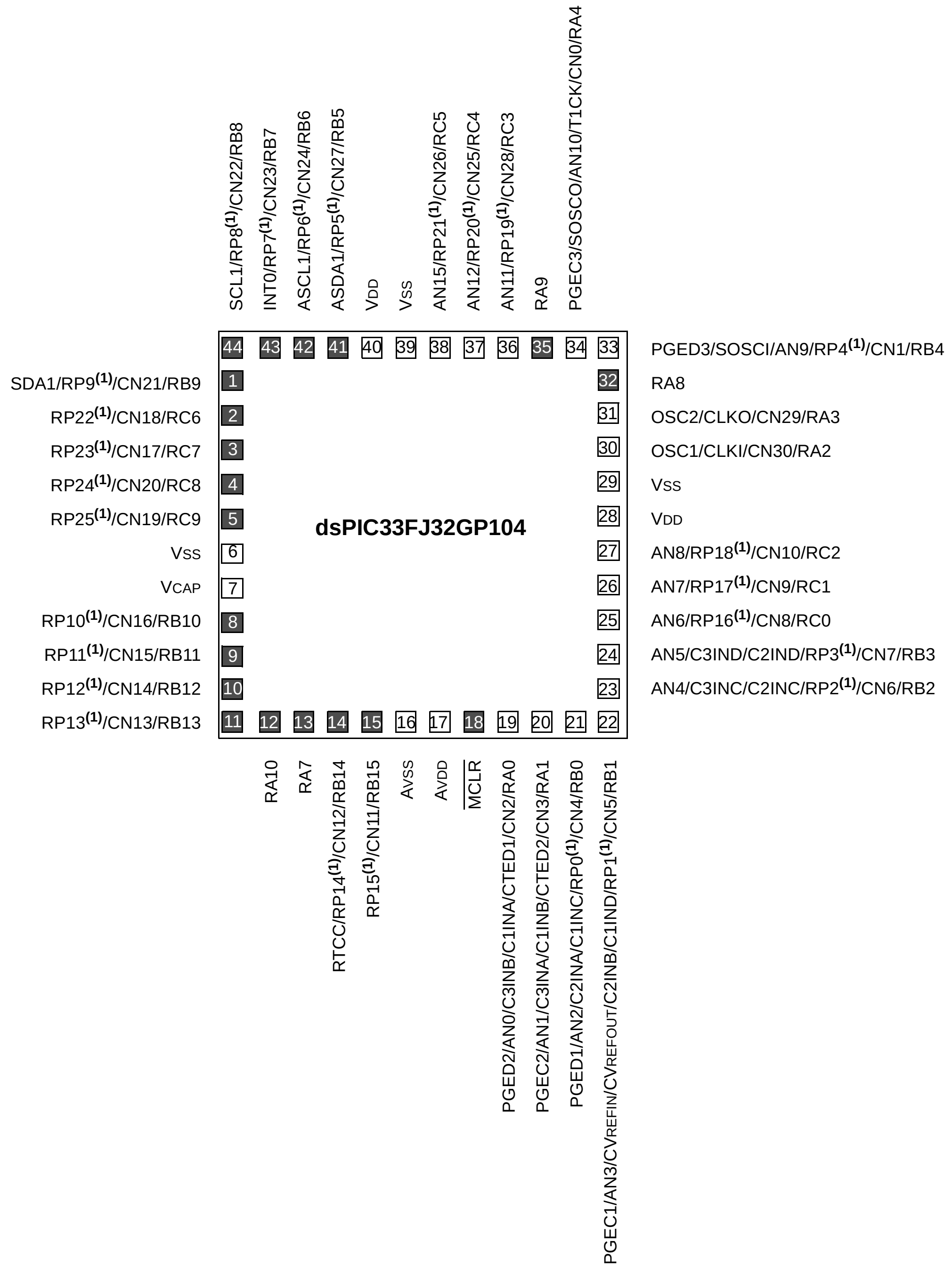
Note 1: The RPn pins can be used by any remappable peripheral. See Table 1 for the list of available peripherals.

2: The PWM Fault pins are enabled and asserted during any Reset event. Refer to **Section 15.2 “PWM Faults”** for more information on the PWM Faults.

Pin Diagrams (Continued)

44-Pin TLA[2]

■ = Pins are up to 5V tolerant



Note 1: The RPn pins can be used by any remappable peripheral. See Table 1 for the list of available peripherals.

2: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

2.7 Oscillator Value Conditions on Device Start-up

If the PLL of the target device is enabled and configured for the device start-up oscillator, the maximum oscillator source frequency must be limited to 4 MHz < F_{IN} < 8 MHz (for MSPLL mode) or 3 MHz < F_{IN} < 8 MHz (for ECPLL mode) to comply with device PLL start-up conditions. HSPLL mode is not supported. This means that if the external oscillator frequency is outside this range, the application must start-up in the FRC mode first. The fixed PLL settings of 4x after a POR with an oscillator frequency outside this range will violate the device operating speed.

Once the device powers up, the application firmware can enable the PLL and then perform a clock switch to the Oscillator + PLL clock source. Note that clock switching must be enabled in the device Configuration Word.

2.8 Configuration of Analog and Digital Pins During ICSP Operations

If MPLAB ICD 3 or MPLAB REAL ICE in-circuit emulator is selected as a debugger, it automatically initializes all of the Analog-to-Digital input pins (ANx) as “digital” pins, by setting all bits in the AD1PCFGL register.

The bits in the register that correspond to the Analog-to-Digital pins that are initialized by MPLAB ICD 3 or MPLAB REAL ICE in-circuit emulator, must not be cleared by the user application firmware; otherwise, communication errors will result between the debugger and the device.

If your application needs to use certain Analog-to-Digital pins as analog input pins during the debug session, the user application must clear the corresponding bits in the AD1PCFGL register during initialization of the ADC module.

When MPLAB ICD 3 or MPLAB REAL ICE in-circuit emulator is used as a programmer, the user application firmware must correctly configure the AD1PCFGL register. Automatic initialization of this register is only done during debugger operation. Failure to correctly configure the register(s) will result in all Analog-to-Digital pins being recognized as analog input pins, resulting in the port value being read as a logic ‘0’, which may affect user application functionality.

2.9 Unused I/Os

Unused I/O pins should be configured as outputs and driven to a logic-low state.

Alternately, connect a 1k to 10k resistor between V_{SS} and unused pins.

REGISTER 3-1: SR: CPU STATUS REGISTER (CONTINUED)

bit 7-5 **IPL<2:0>:** CPU Interrupt Priority Level Status bits[2,3]

111 = CPU Interrupt Priority Level is 7 (15), user interrupts are disabled
110 = CPU Interrupt Priority Level is 6 (14)
101 = CPU Interrupt Priority Level is 5 (13)
100 = CPU Interrupt Priority Level is 4 (12)
011 = CPU Interrupt Priority Level is 3 (11)
010 = CPU Interrupt Priority Level is 2 (10)
001 = CPU Interrupt Priority Level is 1 (9)
000 = CPU Interrupt Priority Level is 0 (8)

bit 4 **RA:** REPEAT Loop Active bit

1 = REPEAT loop is in progress
0 = REPEAT loop is not in progress

bit 3 **N:** MCU ALU Negative bit

1 = Result was negative
0 = Result was non-negative (zero or positive)

bit 2 **OV:** MCU ALU Overflow bit

This bit is used for signed arithmetic (2's complement). It indicates an overflow of a magnitude that causes the sign bit to change state.
1 = Overflow occurred for signed arithmetic (in this arithmetic operation)
0 = No overflow occurred

bit 1 **Z:** MCU ALU Zero bit

1 = An operation that affects the Z bit has set it at some time in the past
0 = The most recent operation that affects the Z bit has cleared it (i.e., a non-zero result)

bit 0 **C:** MCU ALU Carry/$\overline{\text{Borrow}}$ bit

1 = A carry-out from the Most Significant bit of the result occurred
0 = No carry-out from the Most Significant bit of the result occurred

Note 1: This bit can be read or cleared (not set).

2: The IPL<2:0> bits are concatenated with the IPL<3> bit (CORCON<3>) to form the CPU Interrupt Priority Level. The value in parentheses indicates the IPL if IPL<3> = 1. User interrupts are disabled when IPL<3> = 1.

3: The IPL<2:0> Status bits are read-only when NSTDIS = 1 (INTCON1<15>).

REGISTER 3-2: CORCON: CORE CONTROL REGISTER

U-0	U-0	U-0	R/W-0	R/W-0	R-0	R-0	R-0
—	—	—	US	EDT[1]	DL2	DL1	DL0
bit 15							bit 8

R/W-0	R/W-0	R/W-1	R/W-0	R/C-0	R/W-0	R/W-0	R/W-0
SATA	SATB	SATDW	ACCSAT	IPL3[2]	PSV	RND	IF
bit 7							bit 0

Legend:	C = Clearable bit		
R = Readable bit	W = Writable bit	-n = Value at POR	‘1’ = Bit is set
0’ = Bit is cleared	‘x = Bit is unknown	U = Unimplemented bit, read as ‘0’	

bit 15-13 **Unimplemented:** Read as ‘0’

bit 12 **US:** DSP Multiply Unsigned/Signed Control bit

1 = DSP engine multiplies are unsigned
0 = DSP engine multiplies are signed

bit 11 **EDT:** Early DO Loop Termination Control bit[1]

1 = Terminates executing DO loop at the end of current loop iteration
0 = No effect

bit 10-8 **DL<2:0>:** DO Loop Nesting Level Status bits

111 = 7 DO loops are active
•
•
•
001 = 1 DO loop is active
000 = 0 DO loops are active

bit 7 **SATA:** ACCA Saturation Enable bit

1 = Accumulator A saturation is enabled
0 = Accumulator A saturation is disabled

bit 6 **SATB:** ACCB Saturation Enable bit

1 = Accumulator B saturation is enabled
0 = Accumulator B saturation is disabled

bit 5 **SATDW:** Data Space Write from DSP Engine Saturation Enable bit

1 = Data space write saturation is enabled
0 = Data space write saturation is disabled

bit 4 **ACCSAT:** Accumulator Saturation Mode Select bit

1 = 9.31 saturation (super saturation)
0 = 1.31 saturation (normal saturation)

bit 3 **IPL3:** CPU Interrupt Priority Level Status bit 3[2]

1 = CPU Interrupt Priority Level is greater than 7
0 = CPU Interrupt Priority Level is 7 or less

bit 2 **PSV:** Program Space Visibility in Data Space Enable bit

1 = Program space is visible in data space
0 = Program space is not visible in data space

bit 1 **RND:** Rounding Mode Select bit

1 = Biased (conventional) rounding is enabled
0 = Unbiased (convergent) rounding is enabled

bit 0 **IF:** Integer or Fractional Multiplier Mode Select bit

1 = Integer mode is enabled for DSP multiply operations
0 = Fractional mode is enabled for DSP multiply operations

Note 1: This bit will always read as ‘0’.

2: The IPL3 bit is concatenated with the IPL<2:0> bits (SR<7:5>) to form the CPU Interrupt Priority Level.

The SAC and SAC.R instructions store either a truncated (SAC), or rounded (SAC.R) version of the contents of the target accumulator to data memory via the X bus, subject to data saturation (see **Section 3.6.3.2 "Data Space Write Saturation"**). For the MAC class of instructions, the accumulator write-back operation functions in the same manner, addressing combined MCU (X and Y) data space though the X bus. For this class of instructions, the data is always subject to rounding.

3.6.3.2 Data Space Write Saturation

In addition to adder/subtracter saturation, writes to data space can also be saturated, but without affecting the contents of the source accumulator. The data space write saturation logic block accepts a 16-bit, 1.15 fractional value from the round logic block as its input, together with overflow status from the original source (accumulator) and the 16-bit round adder. These inputs are combined and used to select the appropriate 1.15 fractional value as output to write to data space memory.

If the SATDW bit in the CORCON register is set, data (after rounding or truncation) is tested for overflow and adjusted accordingly:

- For input data greater than 0x007FFF, data written to memory is forced to the maximum positive 1.15 value, 0x7FFF.
- For input data less than 0xFF8000, data written to memory is forced to the maximum negative 1.15 value, 0x8000.

The MSb of the source (bit 39) is used to determine the sign of the operand being tested.

If the SATDW bit in the CORCON register is not set, the input data is always passed through unmodified under all conditions.

3.6.4 BARREL SHIFTER

The barrel shifter can perform up to 16-bit arithmetic or logic right shifts, or up to 16-bit left shifts, in a single cycle. The source can be either of the two DSP accumulators or the X bus (to support multi-bit shifts of register or memory data).

The shifter requires a signed binary value to determine both the magnitude (number of bits) and direction of the shift operation. A positive value shifts the operand right. A negative value shifts the operand left. A value of '0' does not modify the operand.

The barrel shifter is 40 bits wide, thereby obtaining a 40-bit result for DSP shift operations and a 16-bit result for MCU shift operations. Data from the X bus is presented to the barrel shifter between Bit Positions 16 and 31 for right shifts, and between Bit Positions 0 and 16 for left shifts.

4.4.3 MODULO ADDRESSING APPLICABILITY

Modulo Addressing can be applied to the Effective Address (EA) calculation associated with any W register. Address boundaries check for addresses equal to:

- The upper boundary addresses for incrementing buffers
- The lower boundary addresses for decrementing buffers

It is important to realize that the address boundaries check for addresses less than or greater than the upper (for incrementing buffers) and lower (for decrementing buffers) boundary addresses (not just equal to). Address changes can, therefore, jump beyond boundaries and still be adjusted correctly.

Note:	The modulo corrected Effective Address is written back to the register only when Pre-Modify or Post-Modify Addressing mode is used to compute the Effective Address. When an address offset (such as [W7 + W2]) is used, Modulo Addressing correction is performed, but the contents of the register remain unchanged.

4.5 Bit-Reversed Addressing

Bit-Reversed Addressing mode is intended to simplify data reordering for radix-2 FFT algorithms. It is supported by the X AGU for data writes only.

The modifier, which can be a constant value or register contents, is regarded as having its bit order reversed. The address source and destination are kept in normal order. Thus, the only operand requiring reversal is the modifier.

4.5.1 BIT-REVERSED ADDRESSING IMPLEMENTATION

Bit-Reversed Addressing mode is enabled in any of these situations:

- BWM<3:0> bits (W register selection) in the MODCON register are any value other than ‘15’ (the stack cannot be accessed using Bit-Reversed Addressing)
- The BREN bit is set in the XBREV register
- The addressing mode used is Register Indirect with Pre-Increment or Post-Increment

If the length of a bit-reversed buffer is M = 2^N bytes, the last ‘N’ bits of the data buffer start address must be zeros.

XB<14:0> is the bit-reversed address modifier, or ‘pivot point,’ which is typically a constant. In the case of an FFT computation, its value is equal to half of the FFT data buffer size.

Note:	All bit-reversed EA calculations assume word-sized data (LSb of every EA is always clear). The XB<14:0> value is scaled accordingly to generate compatible (byte) addresses.

When enabled, Bit-Reversed Addressing is executed only for Register Indirect with Pre-Increment or Post-Increment Addressing and word-sized data writes. It will not function for any other addressing mode or for byte-sized data and normal addresses are generated instead. When Bit-Reversed Addressing is active, the W Address Pointer is always added to the address modifier (XB) and the offset associated with the Register Indirect Addressing mode is ignored. In addition, as word-sized data is a requirement, the LSb of the EA is ignored (and always clear).

Note:	Modulo Addressing and Bit-Reversed Addressing should not be enabled together. If an application attempts to do so, Bit-Reversed Addressing will assume priority when active. For the X WAGU and Y AGU, Modulo Addressing will be disabled. However, Modulo Addressing will continue to function in the X RAGU.

If Bit-Reversed Addressing has already been enabled by setting the BREN (XBREV<15>) bit, a write to the XBREV register should not be immediately followed by an indirect read operation using the W register that has been designated as the Bit-Reversed Pointer.

5.0 FLASH PROGRAM MEMORY

> **Note 1:** This data sheet summarizes the features of the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 family devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Flash Programming"** (DS70191) in the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).
>
> **2:** Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 devices contain internal Flash program memory for storing and executing application code. The memory is readable, writable and erasable during normal operation over the entire VDD range.

Flash memory can be programmed in two ways:

- In-Circuit Serial Programming™ (ICSP™) programming capability
- Run-Time Self-Programming (RTSP)

ICSP allows a device to be serially programmed while in the end application circuit. This is done with two lines for programming clock and programming data (one of the alternate programming pin pairs: PGECx/PGEDx), and three other lines for power (VDD), ground (VSS) and Master Clear ($\overline{\text{MCLR}}$). This allows users to manufacture boards with unprogrammed devices and then program the Digital Signal Controller just before shipping the product. This also allows the most recent firmware or a custom firmware to be programmed.

RTSP is accomplished using `TBLRD` (Table Read) and `TBLWT` (Table Write) instructions. With RTSP, the user application can write program memory data in a single program memory word and erase program memory in blocks or 'pages' of 512 instructions (1536 bytes).

5.1 Table Instructions and Flash Programming

Regardless of the method used, all programming of Flash memory is done with the Table Read and Table Write instructions. These allow direct read and write access to the program memory space, from the data memory, while the device is in normal operating mode. The 24-bit target address in the program memory is formed using bits<7:0> of the TBLPAG register and the Effective Address (EA) from a W register specified in the table instruction, as shown in Figure 5-1.

The `TBLRDL` and the `TBLWTL` instructions are used to read or write to bits<15:0> of program memory. `TBLRDL` and `TBLWTL` can access program memory in both Word and Byte modes.

The `TBLRDH` and `TBLWTH` instructions are used to read or write to bits<23:16> of program memory. `TBLRDH` and `TBLWTH` can also access program memory in Word or Byte mode.

FIGURE 5-1: ADDRESSING FOR TABLE REGISTERS

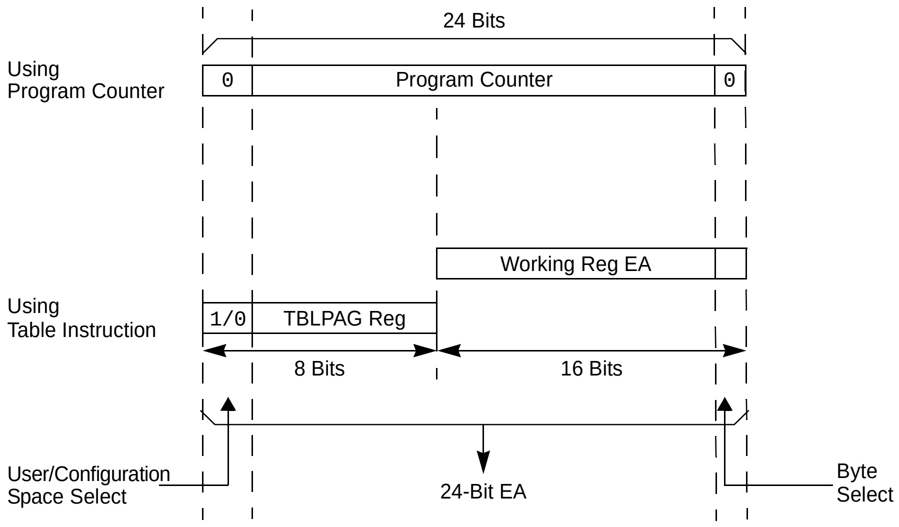
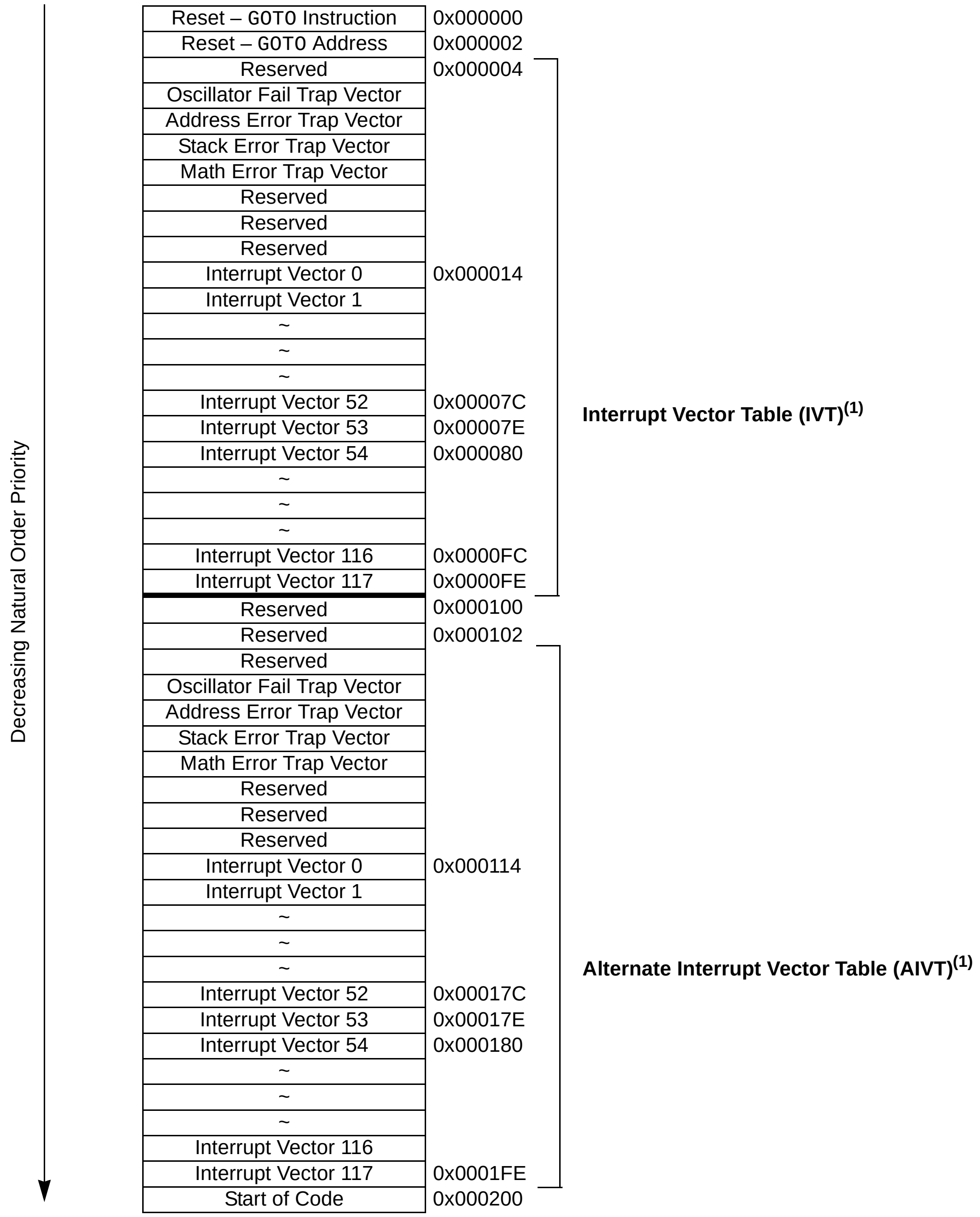


FIGURE 7-1: dsPIC33FJ16(GP/MC)101/102 AND dsPIC33FJ32(GP/MC)101/102/104 INTERRUPT VECTOR TABLE



Reset – `GOTO` Instruction	0x000000
Reset – `GOTO` Address	0x000002
Reserved	0x000004
Oscillator Fail Trap Vector	
Address Error Trap Vector	
Stack Error Trap Vector	
Math Error Trap Vector	
Reserved	
Reserved	
Reserved	
Interrupt Vector 0	0x000014
Interrupt Vector 1	
~	
~	
~	
Interrupt Vector 52	0x00007C
Interrupt Vector 53	0x00007E
Interrupt Vector 54	0x000080
~	
~	
~	
Interrupt Vector 116	0x0000FC
Interrupt Vector 117	0x0000FE
Reserved	0x000100
Reserved	0x000102
Reserved	
Oscillator Fail Trap Vector	
Address Error Trap Vector	
Stack Error Trap Vector	
Math Error Trap Vector	
Reserved	
Reserved	
Reserved	
Interrupt Vector 0	0x000114
Interrupt Vector 1	
~	
~	
~	
Interrupt Vector 52	0x00017C
Interrupt Vector 53	0x00017E
Interrupt Vector 54	0x000180
~	
~	
~	
Interrupt Vector 116	
Interrupt Vector 117	0x0001FE
Start of Code	0x000200

Decreasing Natural Order Priority
Interrupt Vector Table (IVT)(1)
Alternate Interrupt Vector Table (AIVT)(1)

Note 1: See Table 7-1 for the list of implemented interrupt vectors.

REGISTER 7-9: IFS4: INTERRUPT FLAG STATUS REGISTER 4

U-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
—	—	CTMUIF	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0
—	—	—	—	—	—	U1EIF	FLTB1IF[1]
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as ‘0’

bit 13 **CTMUIF:** CTMU Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 12-2 **Unimplemented:** Read as ‘0’

bit 1 **U1EIF:** UART1 Error Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 0 **FLTB1IF:** PWM1 Fault B Interrupt Flag Status bit[1]
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

Note 1: This bit is available in dsPIC(16/32)MC102/104 devices only.

9.5 PMD Control Registers

REGISTER 9-1: PMD1: PERIPHERAL MODULE DISABLE CONTROL REGISTER 1

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	U-0
T5MD[1]	T4MD[1]	T3MD	T2MD	T1MD	—	PWM1MD	—
bit 15							bit 8

R/W-0	U-0	R/W-0	U-0	R/W-0	U-0	U-0	R/W-0
I2C1MD	—	U1MD	—	SPI1MD	—	—	AD1MD[2]
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **T5MD:** Timer5 Module Disable bit[1]
1 = Timer5 module is disabled
0 = Timer5 module is enabled

bit 14 **T4MD:** Timer4 Module Disable bit[1]
1 = Timer4 module is disabled
0 = Timer4 module is enabled

bit 13 **T3MD:** Timer3 Module Disable bit
1 = Timer3 module is disabled
0 = Timer3 module is enabled

bit 12 **T2MD:** Timer2 Module Disable bit
1 = Timer2 module is disabled
0 = Timer2 module is enabled

bit 11 **T1MD:** Timer1 Module Disable bit
1 = Timer1 module is disabled
0 = Timer1 module is enabled

bit 10 **Unimplemented:** Read as '0'

bit 9 **PWM1MD:** PWM1 Module Disable bit
1 = PWM1 module is disabled
0 = PWM1 module is enabled

bit 8 **Unimplemented:** Read as '0'

bit 7 **I2C1MD:** I2C1 Module Disable bit
1 = I2C1 module is disabled
0 = I2C1 module is enabled

bit 6 **Unimplemented:** Read as '0'

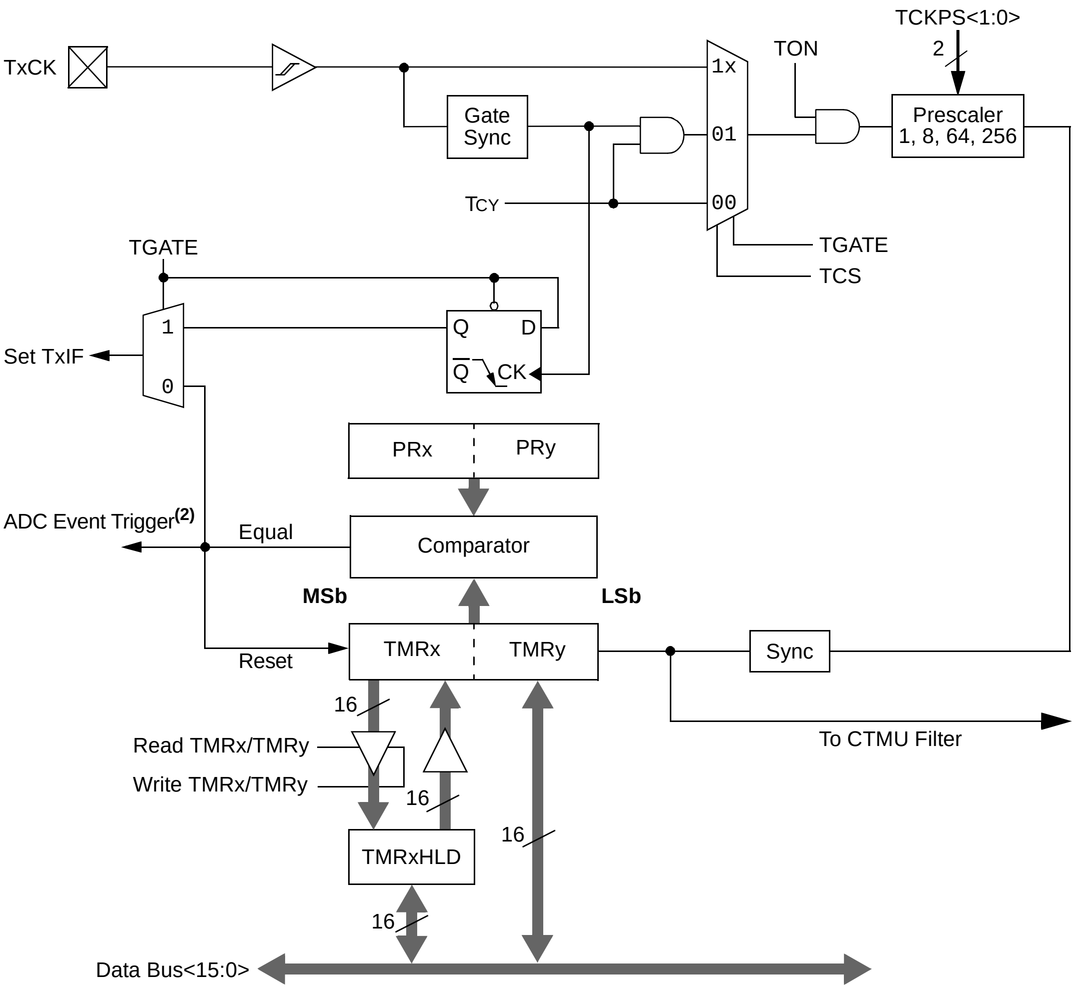
bit 5 **U1MD:** UART1 Module Disable bit
1 = UART1 module is disabled
0 = UART1 module is enabled

bit 4 **Unimplemented:** Read as '0'

Note 1: These bits are available in dsPIC33FJ32(GP/MC)10X devices only.

2: PCFGx bits have no effect if the ADC module is disabled by setting this bit. When the bit is set, all port pins that have been multiplexed with ANx will be in Digital mode.

FIGURE 12-1: TIMER2/3 AND TIMER4/5 (32-BIT) BLOCK DIAGRAM[1,3,4]



Note 1: The 32-bit timer control bit, T32, must be set for 32-bit timer/counter operation. All control bits are respective to the TxCON register.

2: The ADC event trigger is available only on Timer2/3.

3: Timer4/5 is available in dsPIC33FJ32(GP/MC)10X devices only.

4: Where ‘x’ or ‘y’ is present, x = 2 or 4; y = 3 or 5.

13.1 Input Capture Control Register

REGISTER 13-1: ICxCON: INPUT CAPTURE x CONTROL REGISTER

U-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
—	—	ICSIDL	—	—	—	—	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R-0, HC	R-0, HC	R/W-0	R/W-0	R/W-0
ICTMR	ICI1	ICI0	ICOV	ICBNE	ICM2	ICM1	ICM0
bit 7							bit 0

Legend:	HC = Hardware Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as ‘0’

bit 13 **ICSIDL:** Input Capture x Stop in Idle Control bit
1 = Input Capture x module will halt in CPU Idle mode
0 = Input Capture x module will continue to operate in CPU Idle mode

bit 12-8 **Unimplemented:** Read as ‘0’

bit 7 **ICTMR:** Input Capture x Timer Select bits
1 = TMR2 contents are captured on a capture event
0 = TMR3 contents are captured on a capture event

bit 6-5 **ICI<1:0>:** Select Number of Captures per Interrupt bits
11 = Interrupt on every fourth capture event
10 = Interrupt on every third capture event
01 = Interrupt on every second capture event
00 = Interrupt on every capture event

bit 4 **ICOV:** Input Capture x Overflow Status Flag bit (read-only)
1 = Input Capture x overflow occurred
0 = No Input Capture x overflow occurred

bit 3 **ICBNE:** Input Capture x Buffer Empty Status bit (read-only)
1 = Input Capture x buffer is not empty, at least one more capture value can be read
0 = Input Capture x buffer is empty

bit 2-0 **ICM<2:0>:** Input Capture x Mode Select bits
111 = Input Capture x functions as an interrupt pin only when device is in Sleep or Idle mode (rising edge detect only, all other control bits are not applicable)
110 = Unused (module is disabled)
101 = Capture mode, every 16th rising edge
100 = Capture mode, every 4th rising edge
011 = Capture mode, every rising edge
010 = Capture mode, every falling edge
001 = Capture mode, every edge, rising and falling (ICI<1:0> bits do not control interrupt generation for this mode)
000 = Input Capture x module is turned off

EXAMPLE 15-1: ASSEMBLY CODE FOR WRITE-PROTECTED REGISTER UNLOCK AND FAULT CLEARING SEQUENCE

```
; FLTA1 pin must be pulled high externally in order to clear and disable the Fault
; Writing to P1FLTBCON register requires unlock sequence

mov #0xabcd,w10       ; Load first unlock key to w10 register
mov #0x4321,w11       ; Load second unlock key to w11 register
mov #0x0000,w0        ; Load desired value of P1FLTACON register in w0
mov w10, PWM1KEY      ; Write first unlock key to PWM1KEY register
mov w11, PWM1KEY      ; Write second unlock key to PWM1KEY register
mov w0,P1FLTACON      ; Write desired value to P1FLTACON register

; FLTB1 pin must be pulled high externally in order to clear and disable the Fault
; Writing to P1FLTBCON register requires unlock sequence

mov #0xabcd,w10       ; Load first unlock key to w10 register
mov #0x4321,w11       ; Load second unlock key to w11 register
mov #0x0000,w0        ; Load desired value of P1FLTBCON register in w0
mov w10, PWM1KEY      ; Write first unlock key to PWM1KEY register
mov w11, PWM1KEY      ; Write second unlock key to PWM1KEY register
mov w0,P1FLTBCON      ; Write desired value to P1FLTBCON register

; Enable all PWMs using PWM1CON1 register
; Writing to PWM1CON1 register requires unlock sequence

mov #0xabcd,w10       ; Load first unlock key to w10 register
mov #0x4321,w11       ; Load second unlock key to w11 register
mov #0x0077,w0        ; Load desired value of PWM1CON1 register in w0
mov w10, PWM1KEY      ; Write first unlock key to PWM1KEY register
mov w11, PWM1KEY      ; Write second unlock key to PWM1KEY register
mov w0,PWM1CON1       ; Write desired value to PWM1CON1 register
```

EXAMPLE 15-2: C CODE FOR WRITE-PROTECTED REGISTER UNLOCK AND FAULT CLEARING SEQUENCE

```
// FLTA1 pin must be pulled high externally in order to clear and disable the Fault
// Writing to P1FLTACON register requires unlock sequence
// Use builtin function to write 0x0000 to P1FLTACON register
__builtin_write_PWMSFR(&P1FLTACON, 0x0000, &PWM1KEY);

// FLTB1 pin must be pulled high externally in order to clear and disable the Fault
// Writing to P1FLTBCON register requires unlock sequence
// Use builtin function to write 0x0000 to P1FLTBCON register
__builtin_write_PWMSFR(&P1FLTBCON, 0x0000, &PWM1KEY);

// Enable all PWMs using PWM1CON1 register
// Writing to PWM1CON1 register requires unlock sequence
// Use builtin function to write 0x0077 to PWM1CON1 register
__builtin_write_PWMSFR(&PWM1CON1, 0x0077, &PWM1KEY);
```

REGISTER 22-2: CTMUCON2: CTMU CONTROL REGISTER 2

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
EDG1MOD	EDG1POL	EDG1SEL3	EDG1SEL2	EDG1SEL1	EDG1SEL0	EDG2STAT	EDG1STAT
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0
EDG2MOD	EDG2POL	EDG2SEL3	EDG2SEL2	EDG2SEL1	EDG2SEL0	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **EDG1MOD:** Edge 1 Edge Sampling Selection bit
1 = Edge 1 is edge-sensitive
0 = Edge 1 is level-sensitive

bit 14 **EDG1POL:** Edge 1 Polarity Select bit
1 = Edge 1 is programmed for a positive edge response
0 = Edge 1 is programmed for a negative edge response

bit 13-10 **EDG1SEL<3:0>:** Edge 1 Source Select bits
1xxx = Reserved
01xx = Reserved
0011 = CTED1 pin
0010 = CTED2 pin
0001 = OC1 module
0000 = Timer1 module

bit 9 **EDG2STAT:** Edge 2 Status bit
Indicates the status of Edge 2 and can be written to control the edge source.
1 = Edge 2 has occurred
0 = Edge 2 has not occurred

bit 8 **EDG1STAT:** Edge 1 Status bit
Indicates the status of Edge 1 and can be written to control the edge source.
1 = Edge 1 has occurred
0 = Edge 1 has not occurred

bit 7 **EDG2MOD:** Edge 2 Edge Sampling Selection bit
1 = Edge 2 is edge-sensitive
0 = Edge 2 is level-sensitive

bit 6 **EDG2POL:** Edge 2 Polarity Select bit
1 = Edge 2 is programmed for a positive edge response
0 = Edge 2 is programmed for a negative edge response

bit 5-2 **EDG2SEL<3:0>:** Edge 2 Source Select bits
1xxx = Reserved
01xx = Reserved
0011 = CTED2 pin
0010 = CTED1 pin
0001 = Comparator 2 module
0000 = IC1 module

bit 1-0 **Unimplemented:** Read as ‘0’

25.2 MPLAB XC Compilers

The MPLAB XC Compilers are complete ANSI C compilers for all of Microchip's 8, 16, and 32-bit MCU and DSC devices. These compilers provide powerful integration capabilities, superior code optimization and ease of use. MPLAB XC Compilers run on Windows, Linux or MAC OS X.

For easy source level debugging, the compilers provide debug information that is optimized to the MPLAB X IDE.

The free MPLAB XC Compiler editions support all devices and commands, with no time or memory restrictions, and offer sufficient code optimization for most applications.

MPLAB XC Compilers include an assembler, linker and utilities. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. MPLAB XC Compiler uses the assembler to produce its object file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command-line interface
- Rich directive set
- Flexible macro language
- MPLAB X IDE compatibility

25.3 MPASM Assembler

The MPASM Assembler is a full-featured, universal macro assembler for PIC10/12/16/18 MCUs.

The MPASM Assembler generates relocatable object files for the MPLINK Object Linker, Intel® standard HEX files, MAP files to detail memory usage and symbol reference, absolute LST files that contain source lines and generated machine code, and COFF files for debugging.

The MPASM Assembler features include:

- Integration into MPLAB X IDE projects
- User-defined macros to streamline assembly code
- Conditional assembly for multipurpose source files
- Directives that allow complete control over the assembly process

25.4 MPLINK Object Linker/ MPLIB Object Librarian

The MPLINK Object Linker combines relocatable objects created by the MPASM Assembler. It can link relocatable objects from precompiled libraries, using directives from a linker script.

The MPLIB Object Librarian manages the creation and modification of library files of precompiled code. When a routine from a library is called from a source file, only the modules that contain that routine will be linked in with the application. This allows large libraries to be used efficiently in many different applications.

The object linker/library features include:

- Efficient linking of single libraries instead of many smaller files
- Enhanced code maintainability by grouping related modules together
- Flexible creation of libraries with easy module listing, replacement, deletion and extraction

25.5 MPLAB Assembler, Linker and Librarian for Various Device Families

MPLAB Assembler produces relocatable machine code from symbolic assembly language for PIC24, PIC32 and dsPIC DSC devices. MPLAB XC Compiler uses the assembler to produce its object file. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command-line interface
- Rich directive set
- Flexible macro language
- MPLAB X IDE compatibility

TABLE 26-33: SPIx SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 0, SMP = 0) TIMING REQUIREMENTS FOR dsPIC33FJ16(GP/MC)10X

AC CHARACTERISTICS			**Standard Operating Conditions: 2.4V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic[1]**	**Min**	**Typ[2]**	**Max**	**Units**	**Conditions**
SP70	TscP	Maximum SCKx Input Frequency	—	—	15	MHz	See **Note 3**
SP72	TscF	SCKx Input Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP73	TscR	SCKx Input Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP30	TdoF	SDOx Data Output Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP31	TdoR	SDOx Data Output Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{\text{SSx}}$ ↓ to SCKx ↑ or SCKx Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{\text{SSx}}$ ↑ to SDOx Output High-Impedance	10	—	50	ns	See **Note 4**
SP52	TscH2ssH TscL2ssH	$\overline{\text{SSx}}$ after SCKx Edge	1.5 TCY + 40	—	—	ns	See **Note 4**
SP60	TssL2doV	SDOx Data Output Valid after $\overline{\text{SSx}}$ Edge	—	—	50	ns	

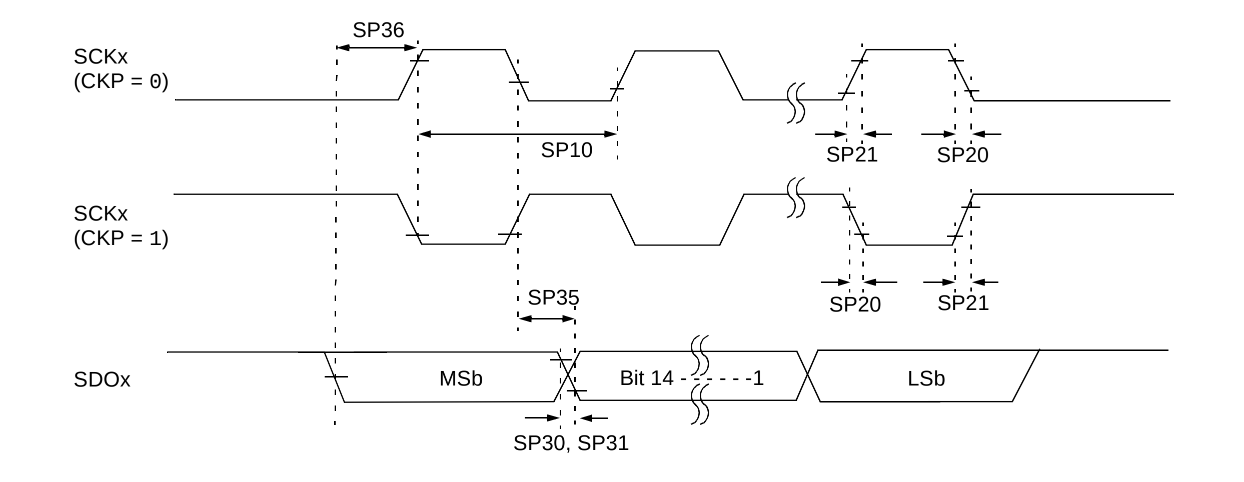
Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in “Typ” column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCKx is 66.7 ns. Therefore, the SCKx clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

FIGURE 26-20: SPIx MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY, CKE = 1) TIMING CHARACTERISTICS FOR dsPIC33FJ32(GP/MC)10X



Note: Refer to Figure 26-1 for load conditions.

TABLE 26-38: SPIx MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY) TIMING REQUIREMENTS FOR dsPIC33FJ32(GP/MC)10X

AC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic[1]**	**Min**	**Typ[2]**	**Max**	**Units**	**Conditions**
SP10	TscP	Maximum SCKx Frequency	—	—	15	MHz	See **Note 3**
SP20	TscF	SCKx Output Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP21	TscR	SCKx Output Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP30	TdoF	SDOx Data Output Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP31	TdoR	SDOx Data Output Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	6	20	ns	
SP36	TdiV2scH, TdiV2scL	SDOx Data Output Setup to First SCKx Edge	30	—	—	ns	

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in “Typ” column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCKx is 66.7 ns. Therefore, the clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

TABLE 26-41: SPIx SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 0, SMP = 0) TIMING REQUIREMENTS FOR dsPIC33FJ32(GP/MC)10X

AC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic[1]**	**Min**	**Typ[2]**	**Max**	**Units**	**Conditions**
SP70	TscP	Maximum SCKx Input Frequency	—	—	15	MHz	See **Note 3**
SP72	TscF	SCKx Input Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP73	TscR	SCKx Input Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP30	TdoF	SDOx Data Output Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP31	TdoR	SDOx Data Output Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{\text{SSx}}$ ↓ to SCKx ↑ or SCKx Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{\text{SSx}}$ ↑ to SDOx Output High-Impedance	10	—	50	ns	See **Note 4**
SP52	TscH2ssH TscL2ssH	$\overline{\text{SSx}}$ after SCKx Edge	1.5 TCY + 40	—	—	ns	See **Note 4**
SP60	TssL2doV	SDOx Data Output Valid after $\overline{\text{SSx}}$ Edge	—	—	50	ns	

Note 1: These parameters are characterized, but are not tested in manufacturing.

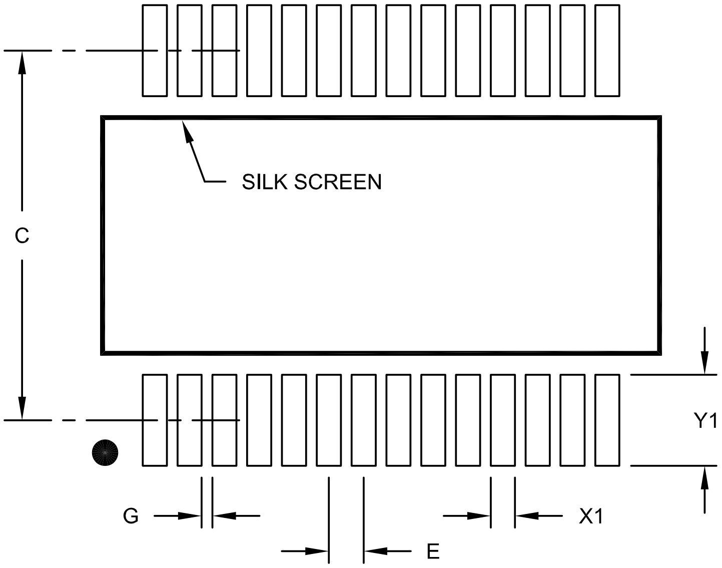
2: Data in “Typ” column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCKx is 66.7 ns. Therefore, the SCKx clock generated by the Master must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

28-Lead Plastic Shrink Small Outline (SS) - 5.30 mm Body [SSOP]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

	Units	MILLIMETERS		
	Dimension Limits	MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Contact Pad Spacing	C		7.20	
Contact Pad Width (X28)	X1			0.45
Contact Pad Length (X28)	Y1			1.75
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2073A